

CLAIMS

What is claimed is:

1. A heat dissipation device comprising:
5 a base; and
a plurality of fins connected to said base and extending out from said base at a non-orthogonal angle to said base.
2. The heat dissipation device of Claim 1 wherein said non-orthogonal angle is substantially forty-five degrees.
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3. The heat dissipation device of Claim 1 wherein said heat dissipation device is configured to be thermally coupled to an electronic component for dissipating heat generated by said electronic component.
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4. The heat dissipation device of Claim 3 wherein said electronic component is a microprocessor.
5. The heat dissipation device of Claim 1 wherein said heat
20 dissipation apparatus is comprised of aluminum.
6. The heat dissipation device of Claim 1 wherein said heat dissipation apparatus is comprised of copper.
- 25 7. The heat dissipation device of Claim 1 further comprising a fan disposed perpendicular to said plurality of fins, said fan for moving air across said plurality of fins.
8. An electronic device comprising:
30 a computer component; and

5 a tilted fin heat sink thermally coupled to said computer component for dissipating heat generated by said computer component, said tilted fin heat sink comprising a base and a plurality of fins, wherein said plurality of fins extend out from said base of said heat sink at a non-orthogonal angle to said base, said tilted fin heat sink for dissipating heat generated by said computer component.

10 9. The electronic device of Claim 8 wherein said non-orthogonal angle is substantially forty-five degrees.

10 10. The electronic device of Claim 8 wherein said tilted fin heat sink is comprised of aluminum.

15 11. The electronic device of Claim 8 wherein said tilted fin heat sink is comprised of copper.

20 12. The electronic device of Claim 8 further comprising a fan disposed perpendicular to said plurality of fins, said fan for moving air across said plurality of fins.

13. The electronic device of Claim 8 wherein said computer component is a microprocessor.

25 14. A circuit board comprising:
a card connector for connecting to a card such that said card extends out from said card connector at a first non-orthogonal angle to said card connector;
an electronic component; and
30 a tilted fin heat sink mounted to said electronic component, wherein fins of said heat sink extend out from a base of said heat sink at a second non-orthogonal angle to said base; and

wherein said card connector and said electronic component are proximately placed such that said card and said fins do not come in contact.

5 15. The circuit board of Claim 14 wherein said first non-orthogonal angle and said second non-orthogonal angle are substantially equal.

 16. The circuit board of Claim 15 wherein said first non-orthogonal angle and said second non-orthogonal angle are substantially forty-five degrees.

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 17. The circuit board of Claim 14 wherein said card and said fins are substantially parallel.

 18. The circuit board of Claim 14 wherein said card is a dual in-line memory module (DIMM).

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 19. The circuit board of Claim 14 wherein said electronic component is a microprocessor.

20 20. The circuit board of Claim 14 wherein said electronic component is an integrated circuit.

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